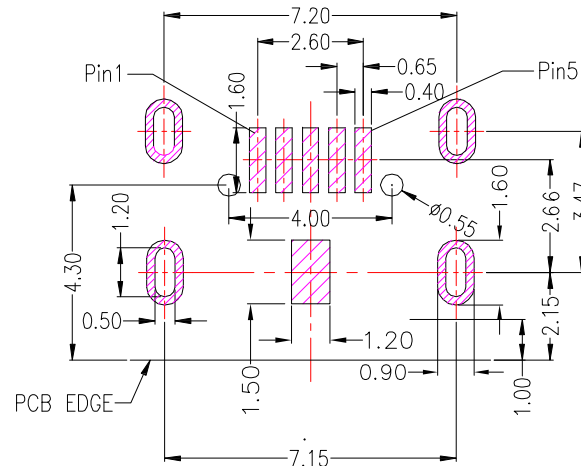
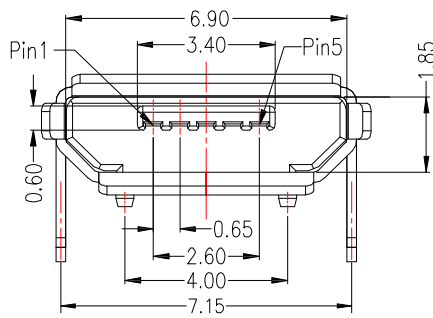
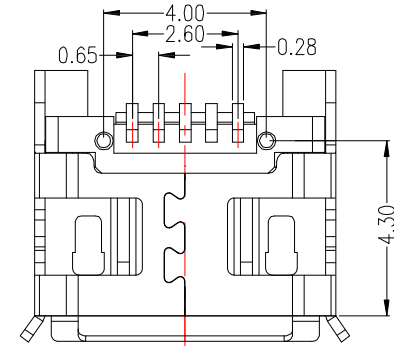
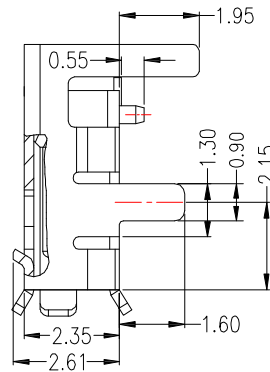
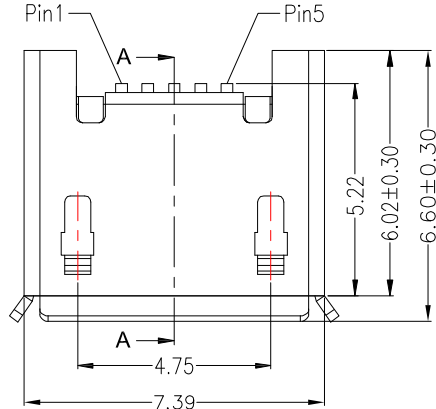


SECTION A-A



P.C.B LAYOUT MOUNTING PATTERN

NOTES:

MATERIAL:

- 1.1 HOUSING: LCP
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: BRASS

Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.8 A(PIN1&5) MAX,1.0 A(PIN2&3&4) MAX
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 V(ac) FOR 1min
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 TOTAL MATING FORCE: 3.57 KgF MAX.
- 3.6 TOTAL UNMATING FORCE: 1.0 KgF MIN.
- 3.7 TEMPERATURE RANGE: -30°C ~ +80°C

8	新增PCB LAYOUT尺寸和更新底部樣式	Jack	081624
7	新增尺寸	Jack	121319
6	新增尺寸	Jack	121219
5	更新樣式	Lan	050619
4	更新底部樣式	Jack	030419
ITEM NO.	DESCRIPTION	DRAWN	DATE



TOLERANCE UNLESS OTHERWISE STATED :
 Up to 5 ±0.2
 Above 5 ~ 15 ±0.3
 Above 15 ~ 30 ±0.4
 Above 30 ~ 50 ±0.5
 Angle ±0.3

3RD. ANGEL'S

UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	08/16/24			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB B TYPE SHELL DIPx4: 7.15 ; W/embossing
Jacky Chen	08/16/24			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-ED7NI-S347
Tony Kao	08/16/24	1 : 1	PART NO.	MRUSB-5B-ED7NI-S347
		SHEET NO.	1 of 1	
			SIZE	A4
			VER	R8